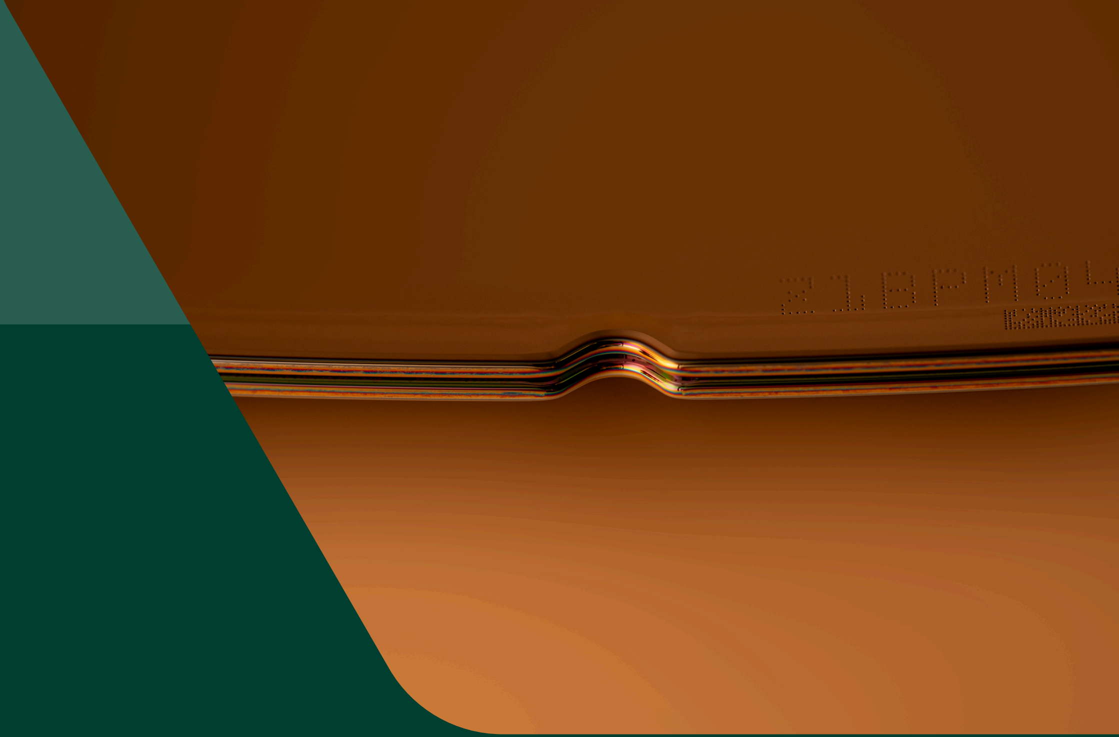

XB 8

Growing Innovation

SUSS

Universal bonding solution

The XB8 combines process flexibility with high bond force. Designed for a wide range of bonding processes, this semi-automated system supports bond stacks with wafer sizes up to 200 mm.

Temperature, chamber pressure, bond force: The XB8 wafer bonder provides high performance and offers full control over all process parameters – making it ideally suited for both R&D as well as volume production in the fields of MEMS, advanced packaging, 3D integration and engineered substrates. It offers advanced process automation to minimize operator influence and maximize repeatability while closely control temperature distribution across the wafer by SUSS's unique dual-zone heating system.

Dual zone heaters up to 500 °C

Homogeneous and high-speed processing

Three-zone force control up to 100 kN

We are committed to driving the next chapter of innovation and growth in the advanced backend together.

XB8
Highlights

Independent dual-zone ceramic heaters with active air cooling on both top and bottom sides

A maximum temperature of 500 °C delivering uniform heating, excellent results and maintains control accuracy at setpoint

A recipe-controlled chamber pressure, adjustable from 3000 mbar abs down to 5×10^{-5} mbar

A recipe controlled tool force up to 100 kN and three tool forces zones to match the standard wafer sizes

XB8
Technical data

General	
Substrate Size	100 / 150 / 200 mm wafers
Dimensions (WxDxH)	1469 mm x 778 mm x 1710 mm
Electrical connection panel	network connection, power cable input, roughing pump AC connector, spare connector, connector for pumps, chiller, cool plate
Pneumatic connection panel	High pressure input, cooling water connection, roughing pump connection, heat exhaust, general exhaust, process gas inputs, cooling air, VAC-input, CDA-input, N2-input
Power Input	400 VAC / 25 A at 50 Hz (L1, L2, L3, N, PE) 208 VAC / 40 A at 60 Hz (L1, L2, L3, PE)
Relevant EC-Directives	2006/42/EC Machinery Directive 2014/35/EC Low Voltage Directive 2014/30/EC EC Directive

XB8 Scroll Pump	
Dimensions (WxDxH)	304 mm x 419 mm x 265 mm
Voltage Supply	100 - 127 / 200 - 240 V AC (± 10 %) 50 Hz / 60 Hz
Weight	24 kg

XB8 Chiller	
Dimensions (WxDxH)	500 mm x 760 mm x 640 mm
Multi-voltage and multi frequency input	230 V / 50 Hz & 220 V / 60 Hz

Data, design and specification depend on individual process conditions and can vary according to equipment configurations. Not all specifications may be valid simultaneously. Illustrations, photos and specifications in this brochure are not legally binding. SUSS reserves the right to change machine specifications without prior notice.

Growing Innovation

SUSS

Visit **www.suss.com/locations** to find our nearest company representative or contact us directly:

SUSS MicroTec SE
suss.com

Version
TDS_XB8_2026 · 01